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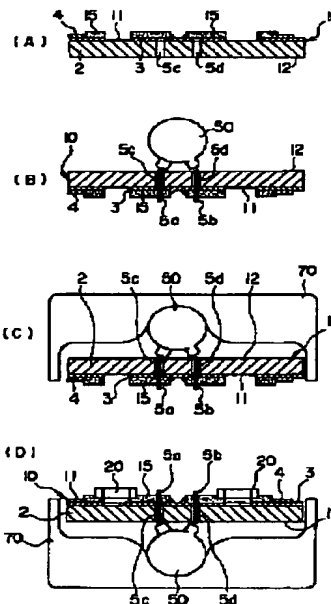
(54) **REFLOW SOLDERING METHOD**

(57) Abstract:

**PURPOSE:** To reduce manhours, and line equipment, and to reduce heat stress to a part by enabling reflow soldering of a surface mount part, and an insertion part to a substrate simultaneously.

**CONSTITUTION:** The method includes a process for applying cream solder 15 to one surface 11 of a substrate 10, a process for inserting an insertion part 20 to the substrate 10 from a side of the other surface 12, a process for temporarily fixing the insertion part 20 to the substrate 10 against drop-off, a process for mounting the surface mount part 20 on the substrate 10, and a process for performing reflow soldering for the surface mounting part 20 and the temporarily fixed insertion part 50 simultaneously.

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